

# Determination of the Relative Defect Density in Semiconductors Using SPA-TCT and TPA-TCT Method

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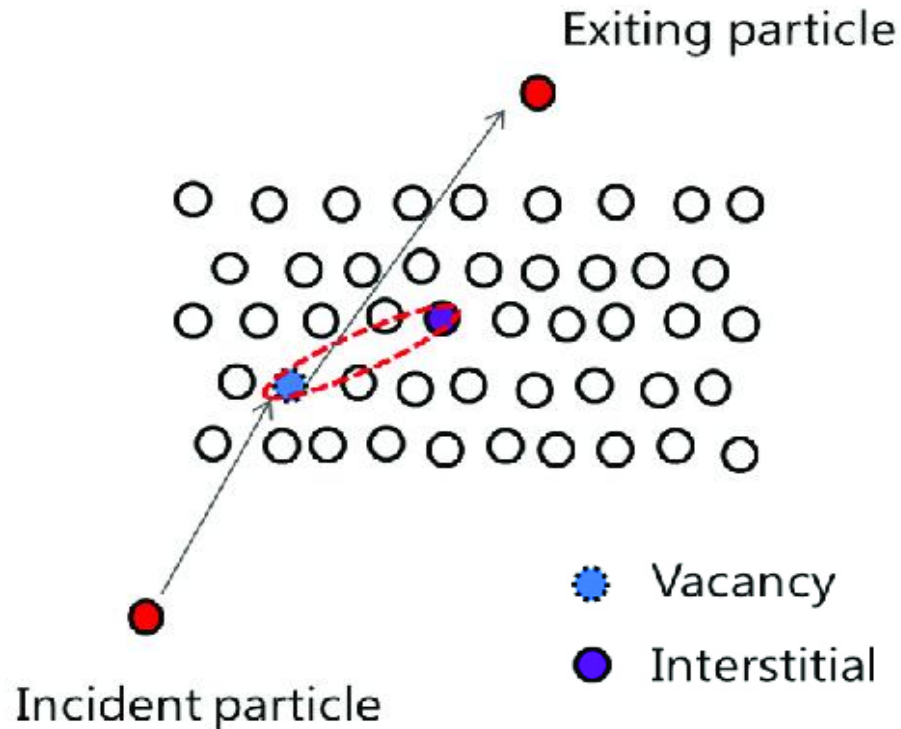
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Source: Madiba et al. (2023), *Materials Today: Proceedings*

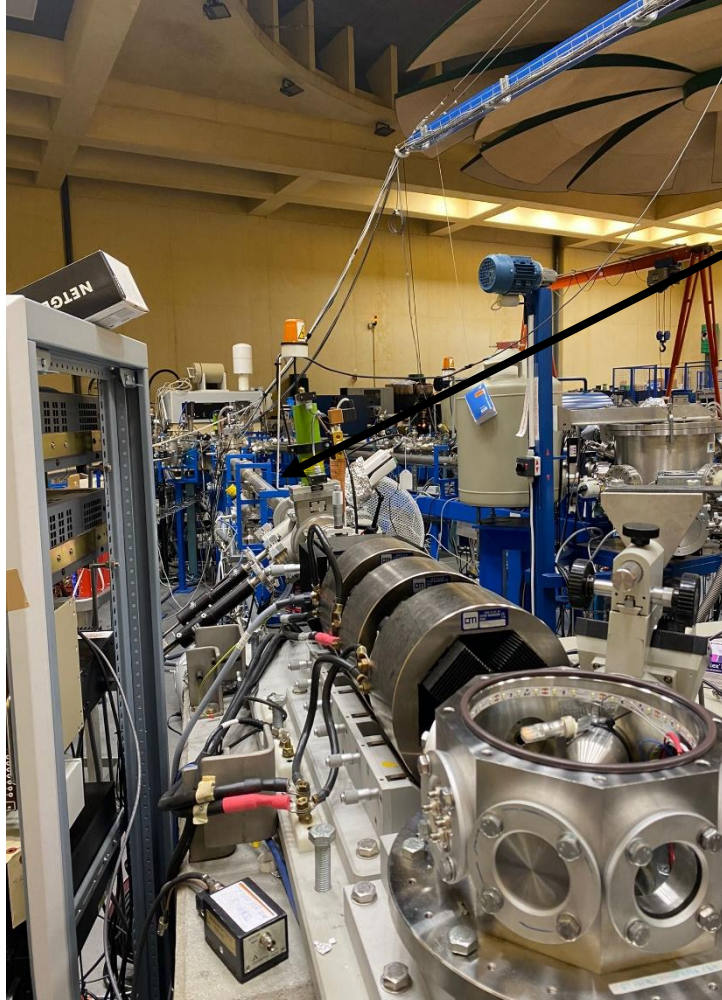
## Effect of Lattice Damage on Semiconductor Performance

- **Ion implantation** displaces atoms, creating vacancies and interstitials.
- These **defects** introduce trap levels and recombination centers in the bandgap.
- Carrier mobility, lifetime, and **charge collection efficiency decrease**.
- Leakage current increases and the **detector response degrades**.

### Goal:

To study the sensitivity of SPA-TCT and TPA-TCT to ion implantation-induced damage

# Microprobe beam line at CNA



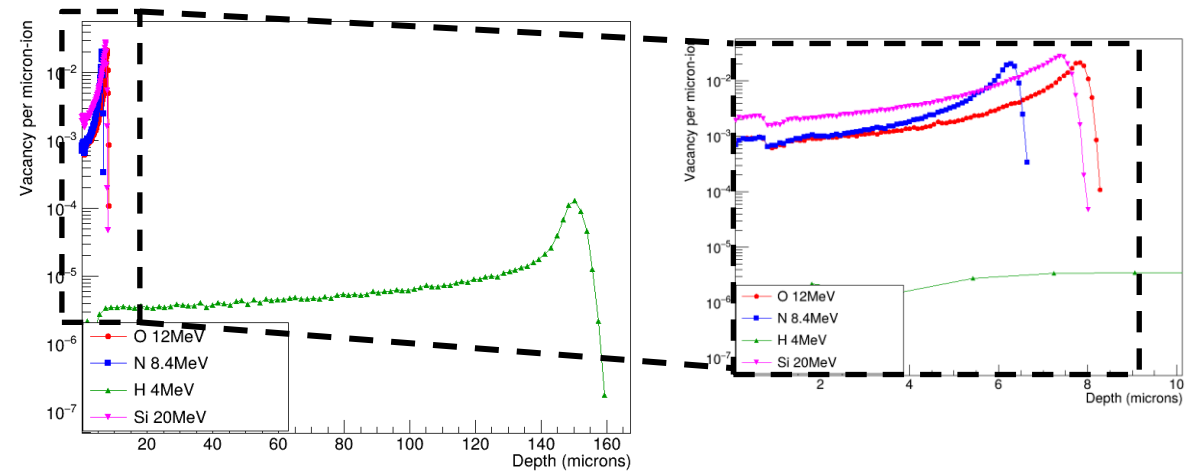
**Nuclear Microprobe line**



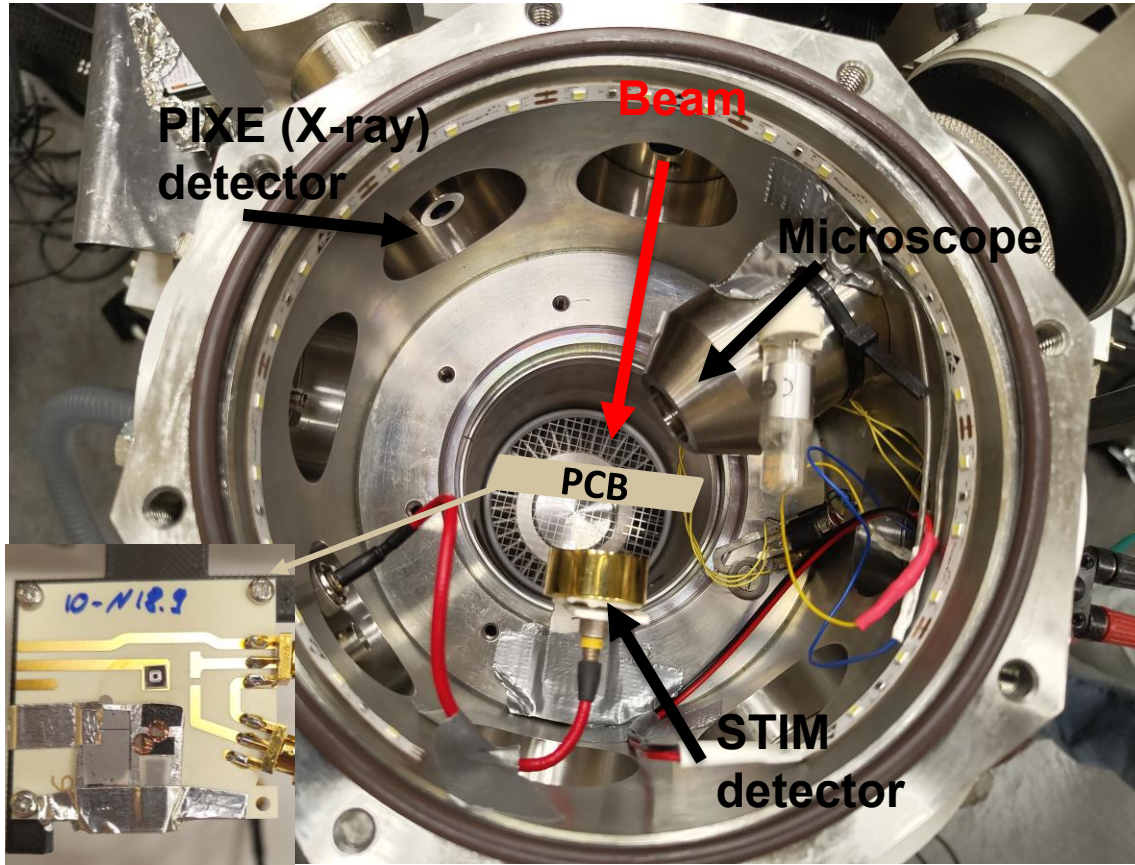
**Tandem room**

Different ion implantations in silicon **PIN** diodes :

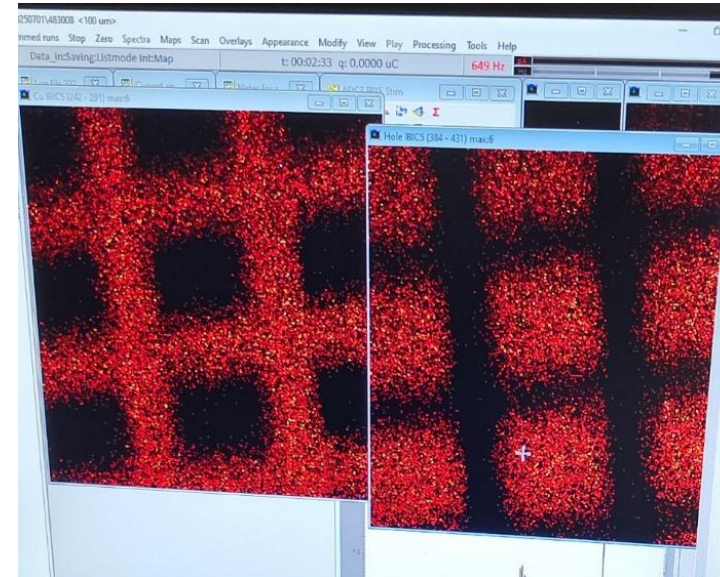
- 4 MeV H<sup>+</sup>
- 12 MeV O<sup>5+</sup>
- 20 MeV Si<sup>8+</sup>
- 8.4 MeV N<sup>4+</sup>



# Experimental setup at CNA



Nuclear Microprobe chamber



Grid dimension :

Pitch : 83  $\mu\text{m}$

Bar width : 25  $\mu\text{m}$

Hole width : 58  $\mu\text{m}$

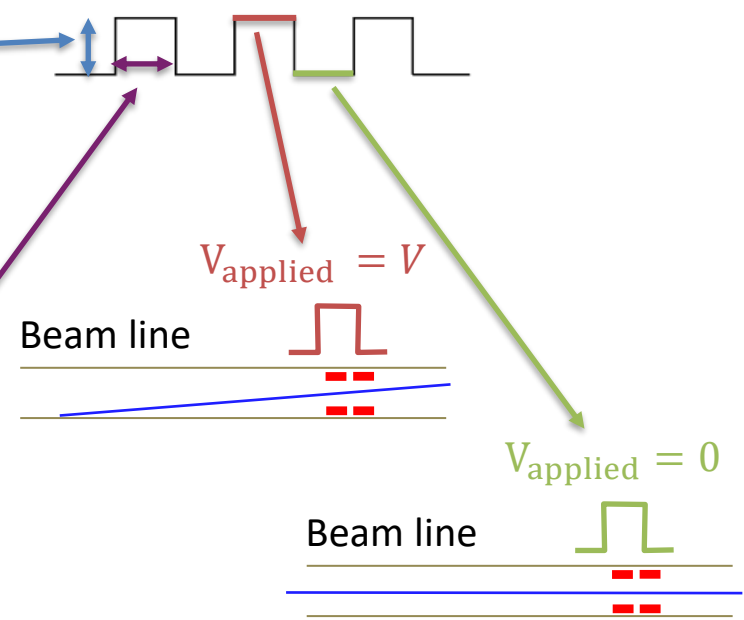
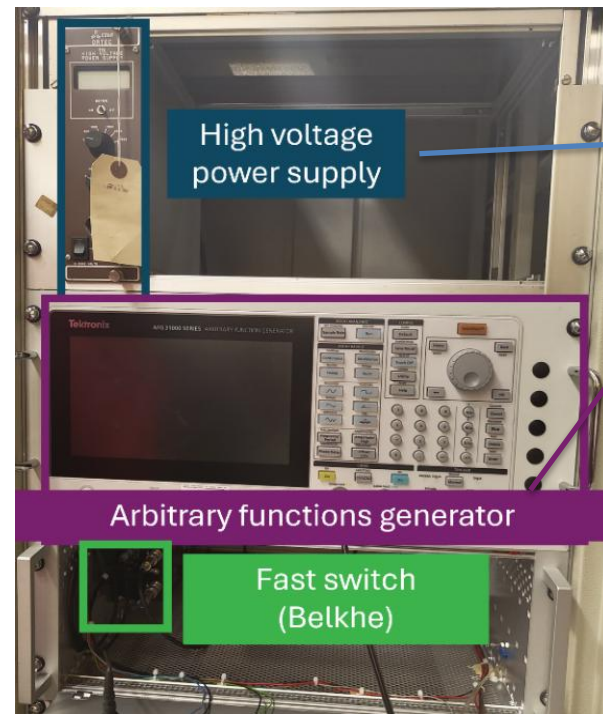
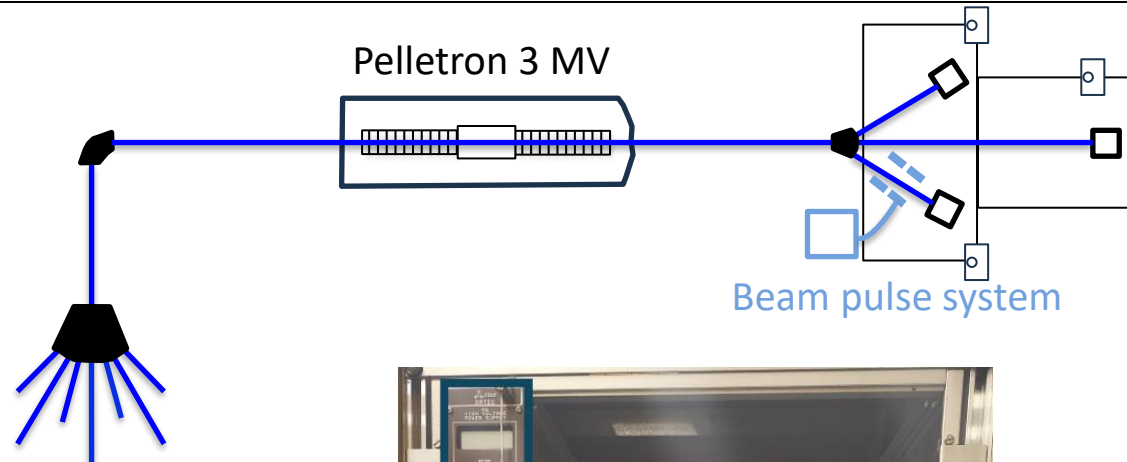
Raster scan :  
200 x 200  $\mu\text{m}$

## STIM (Scanning transmission ion microscopy) technique

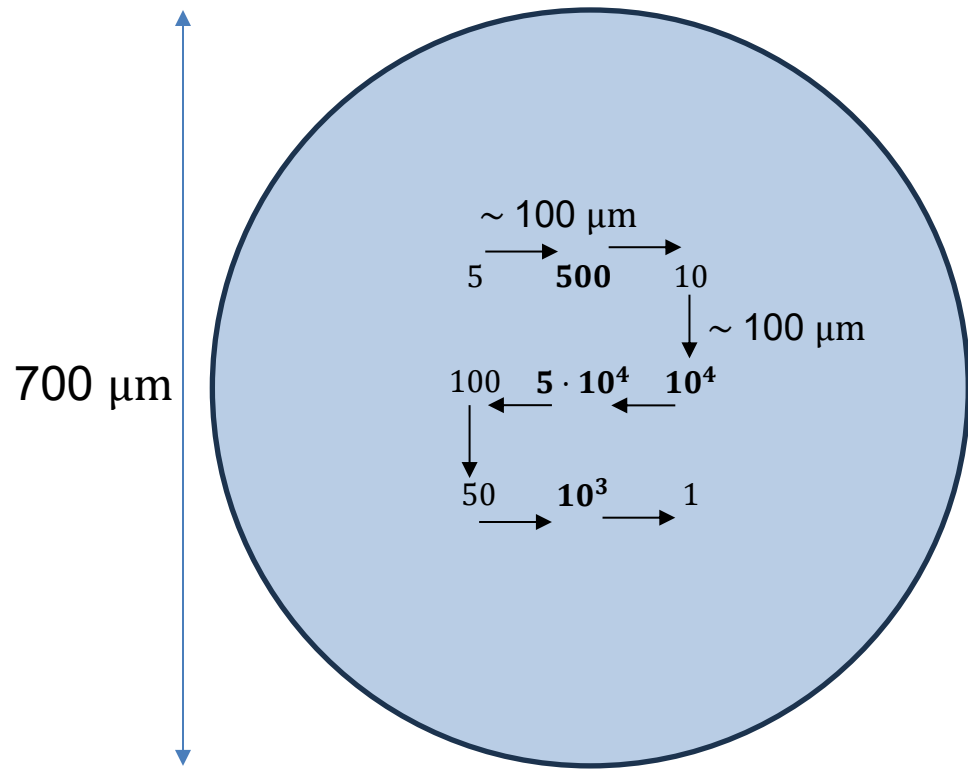
- Accurate **beam size**.
- Silicon detector used for STIM allows to select the ion rate and the **electronic chain gain** before irradiating the diodes with each different ion beam..

# Implantation experiment at CNA

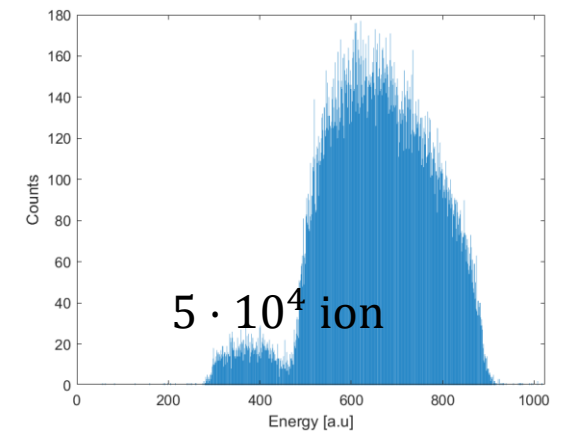
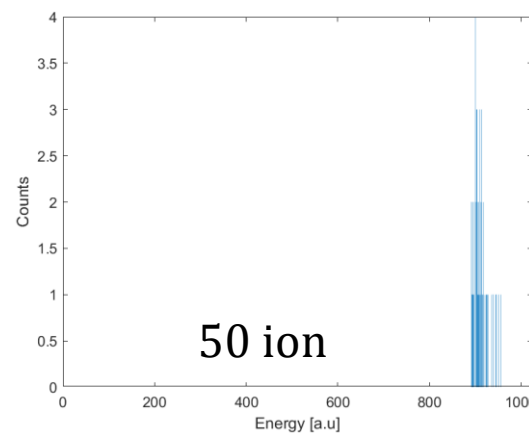
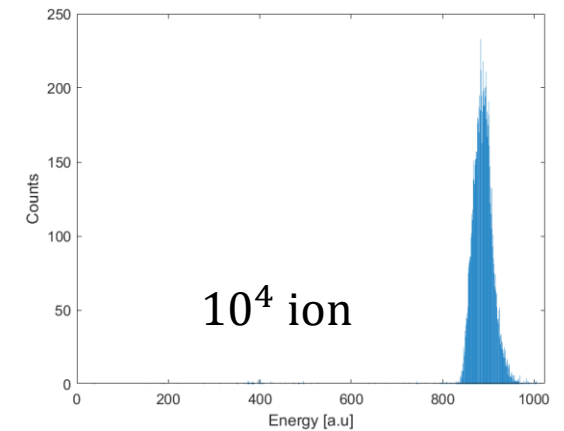
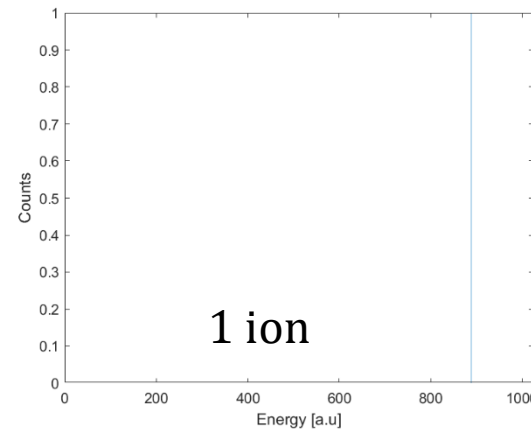
- Stable beam conditions are required for implantation.
- Goal: implant from 1 to  $\sim 10^5$  ions per zone.
- Microprobe slits reduce beam current to  $\sim 1000$  ions/s.
- Beam pulse system enables control of implanted zones with very few ions.



# Implantation experiment at CNA

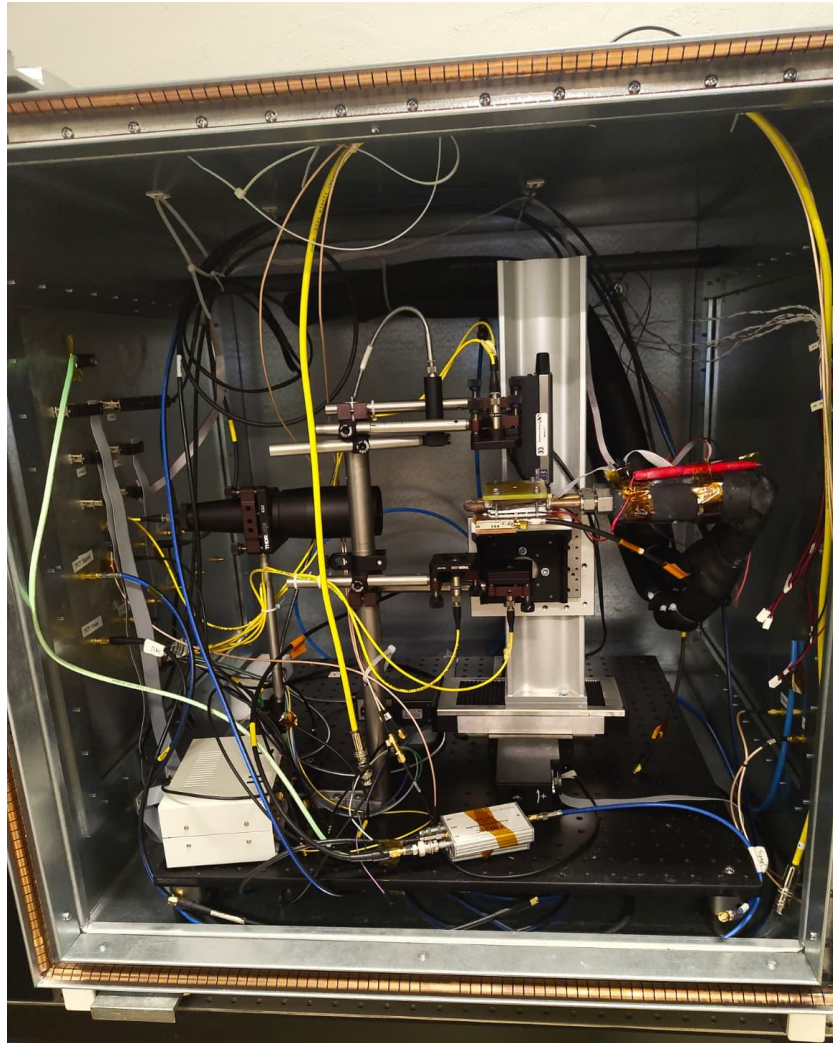


Number of ions implanted



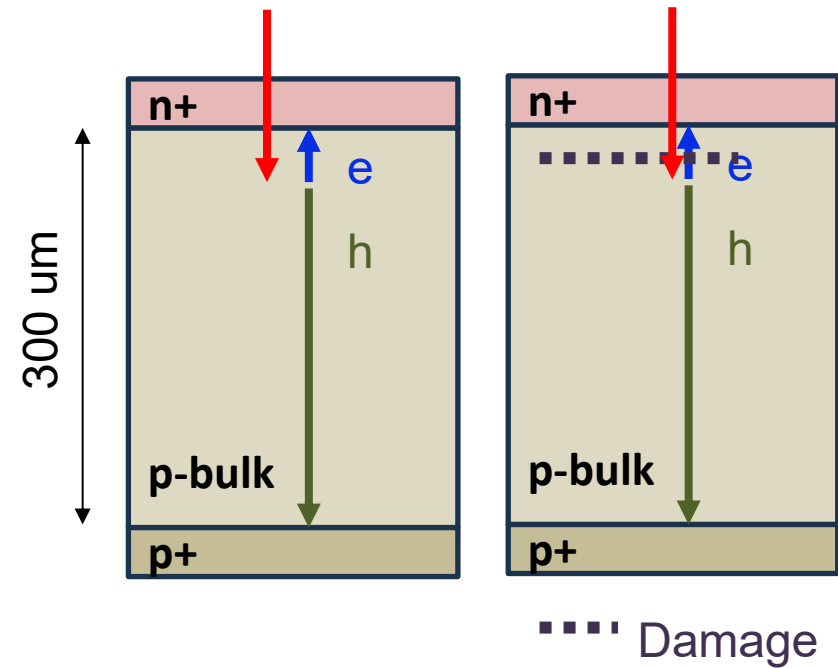
Ion implantation measured with DUT ( $V = 80 \text{ V}$ )

# SPA-TCT at CERN



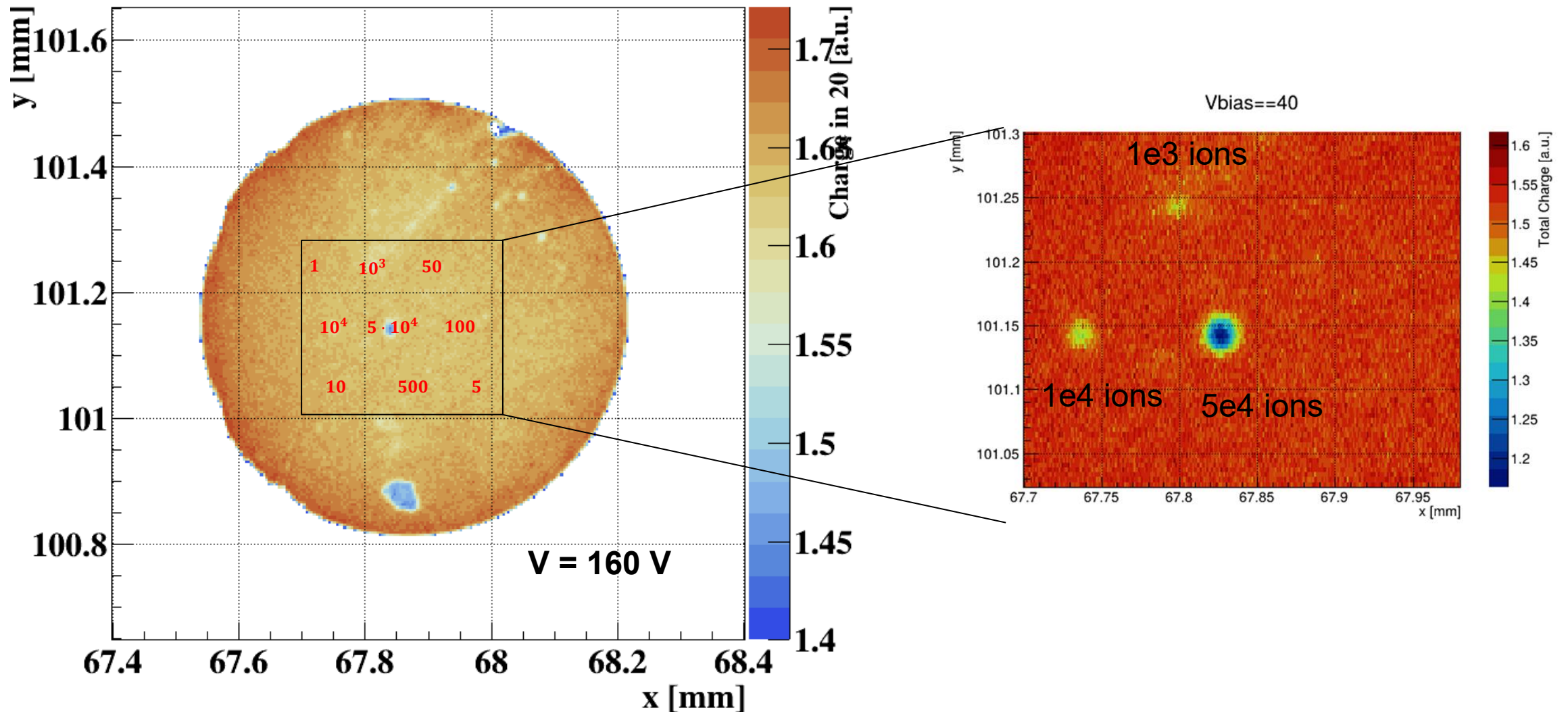
## TCT: red laser (650nm = 1.9 eV)

- short penetration depth: carriers created in a few  $\mu\text{m}$  from surface
- front and back TCT: study electron and hole drift
- 2D spatial resolution (5-10 $\mu\text{m}$ )

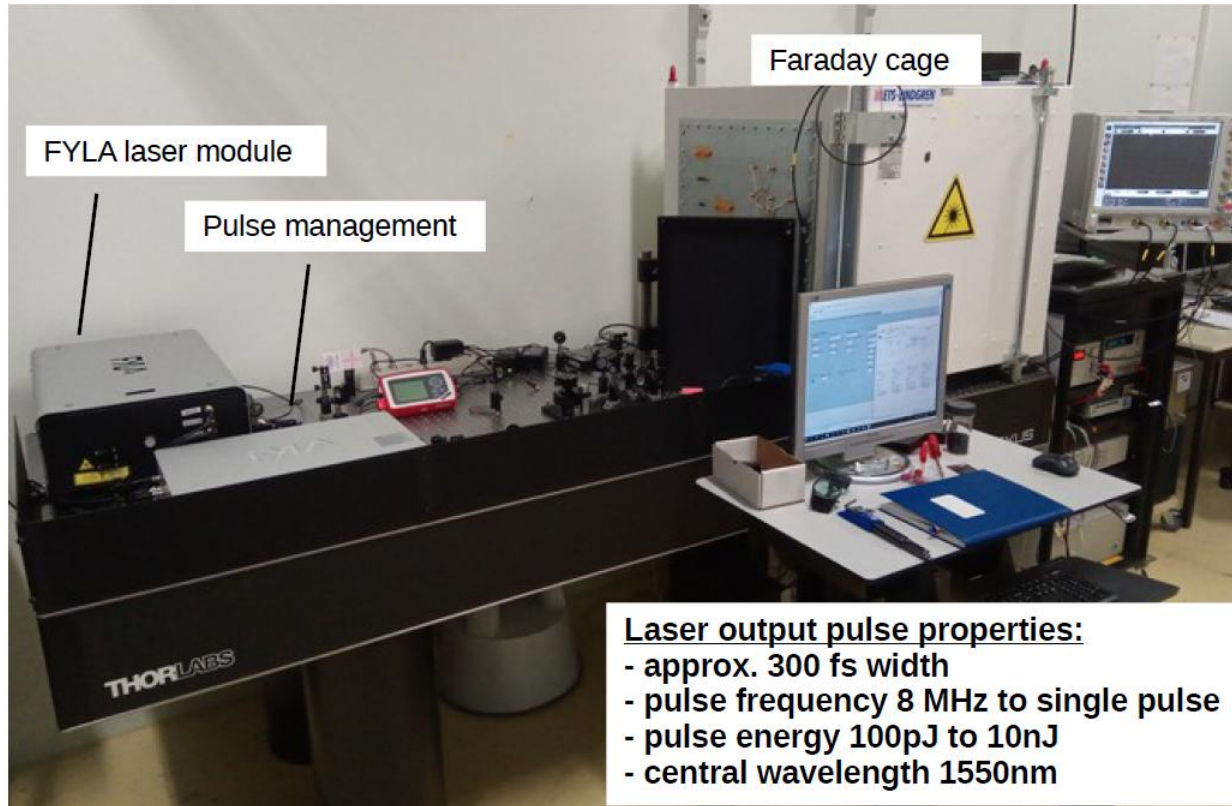


# SPA-TCT on Si implanted DUT

TCT: red laser (650nm = 1.9 eV)

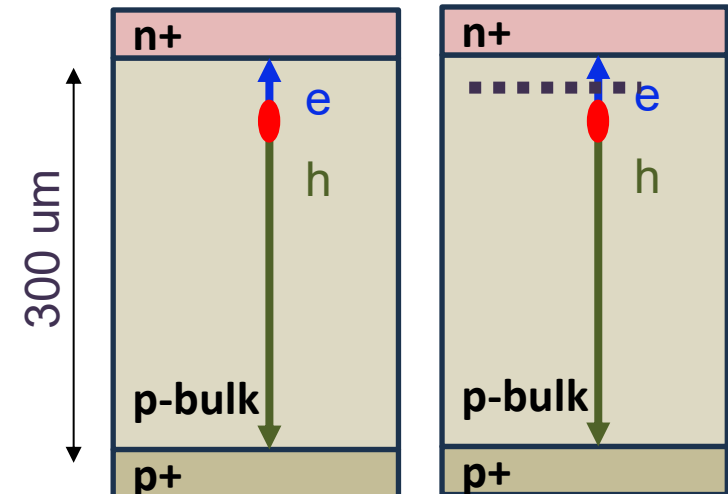


# TPA-TCT at CERN



## TPA-TCT: SWIR laser (1550nm = 0.8 eV)

- No single photon absorption in silicon
- 2 photons produce one electron-hole pair
- Point-like energy deposition in focal point
- 3D spatial resolution ( $1 \times 1 \times 10 \mu\text{m}^3$ )

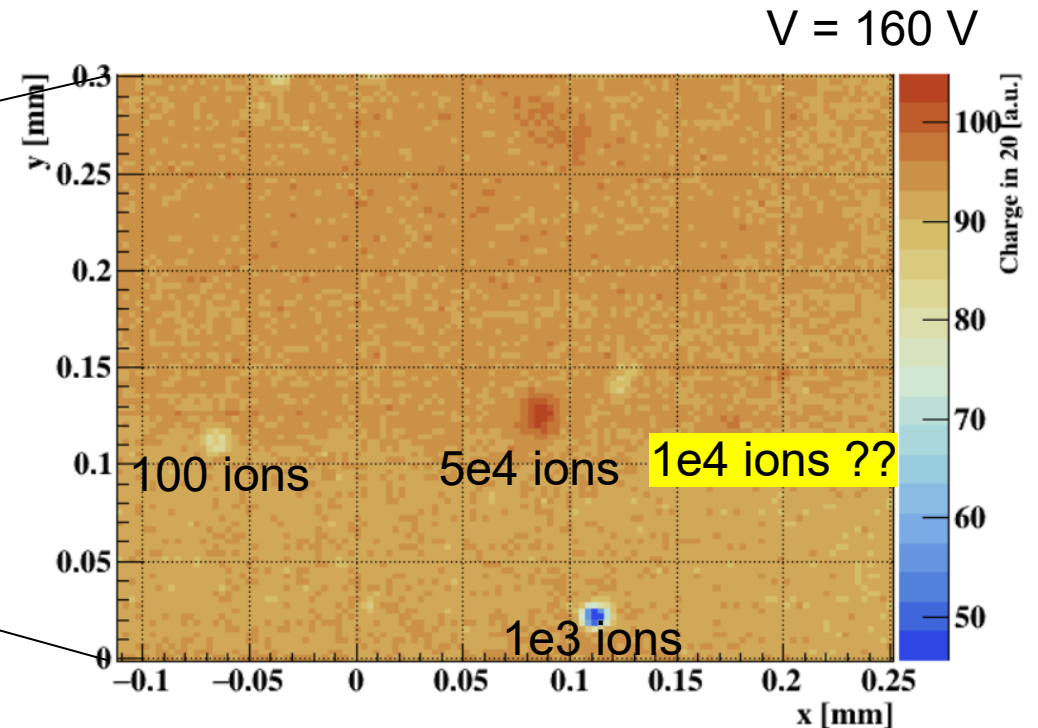
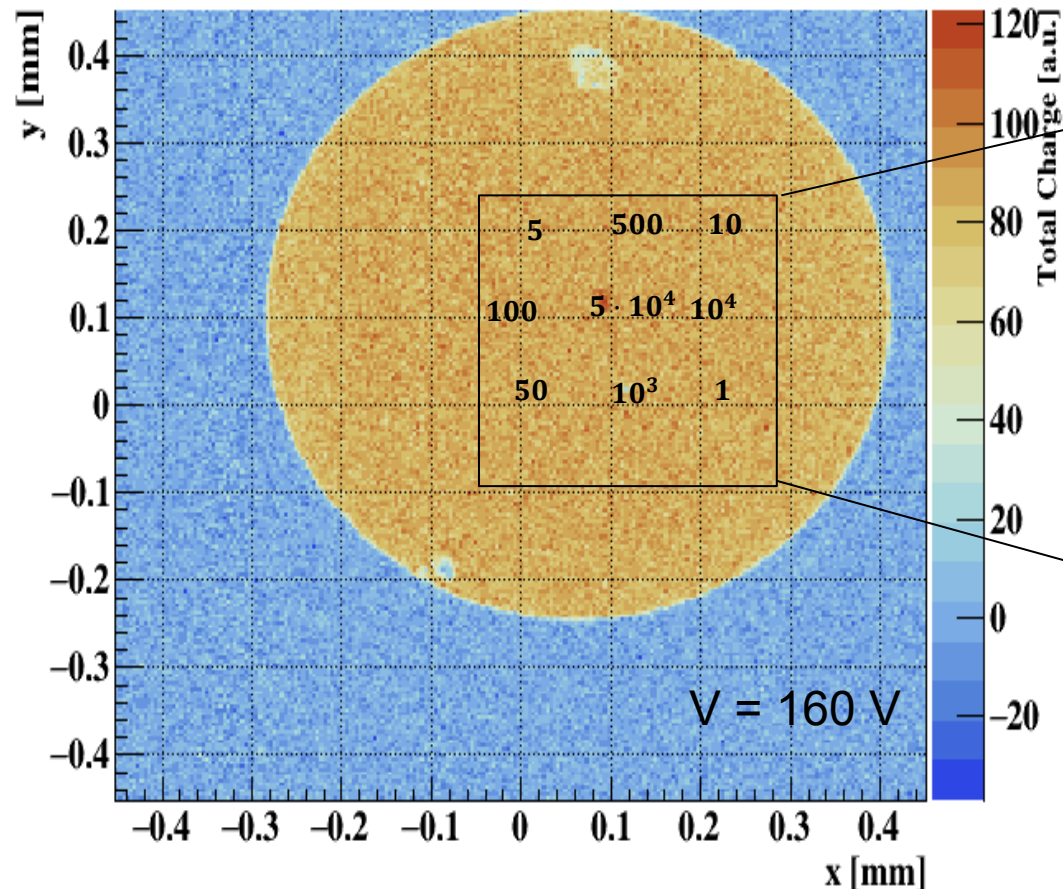


... Damage

For more information: see PhD thesis M. Wiehe (2021), S. Pape (2024)

# TPA-TCT on Si implanted DUT

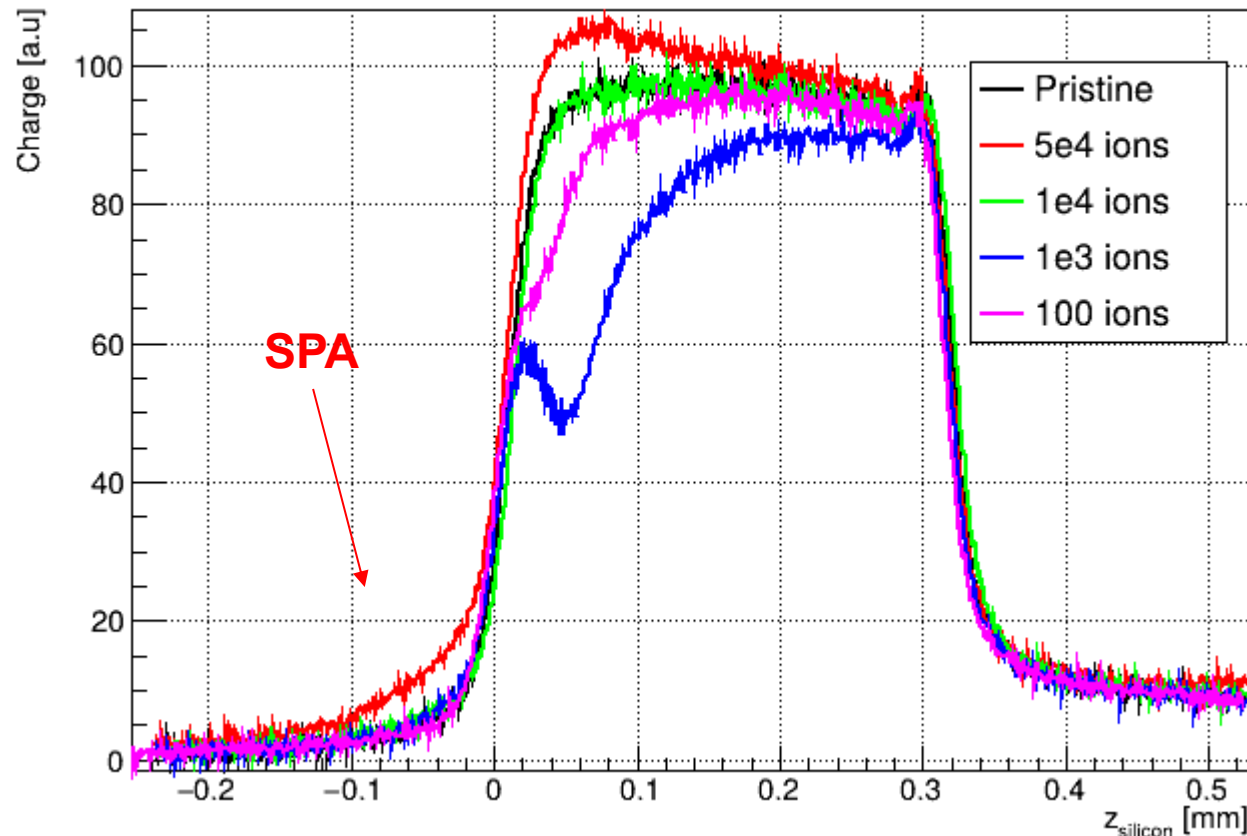
TPA-TCT: SWIR laser (1550nm = 0.8 eV)



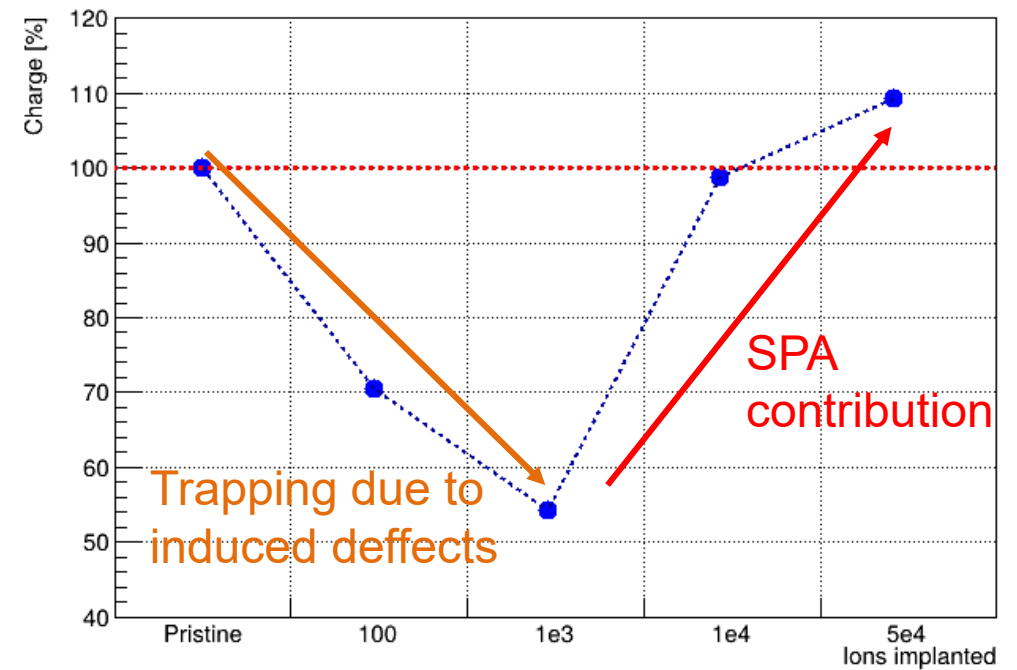
XY scan done at around 50 microns into silicon  
(Maximum difference in Charge versus z plots)

# TPA-TCT on Si implanted DUT

## TPA-TCT: SWIR laser (1550nm = 0.8 eV)

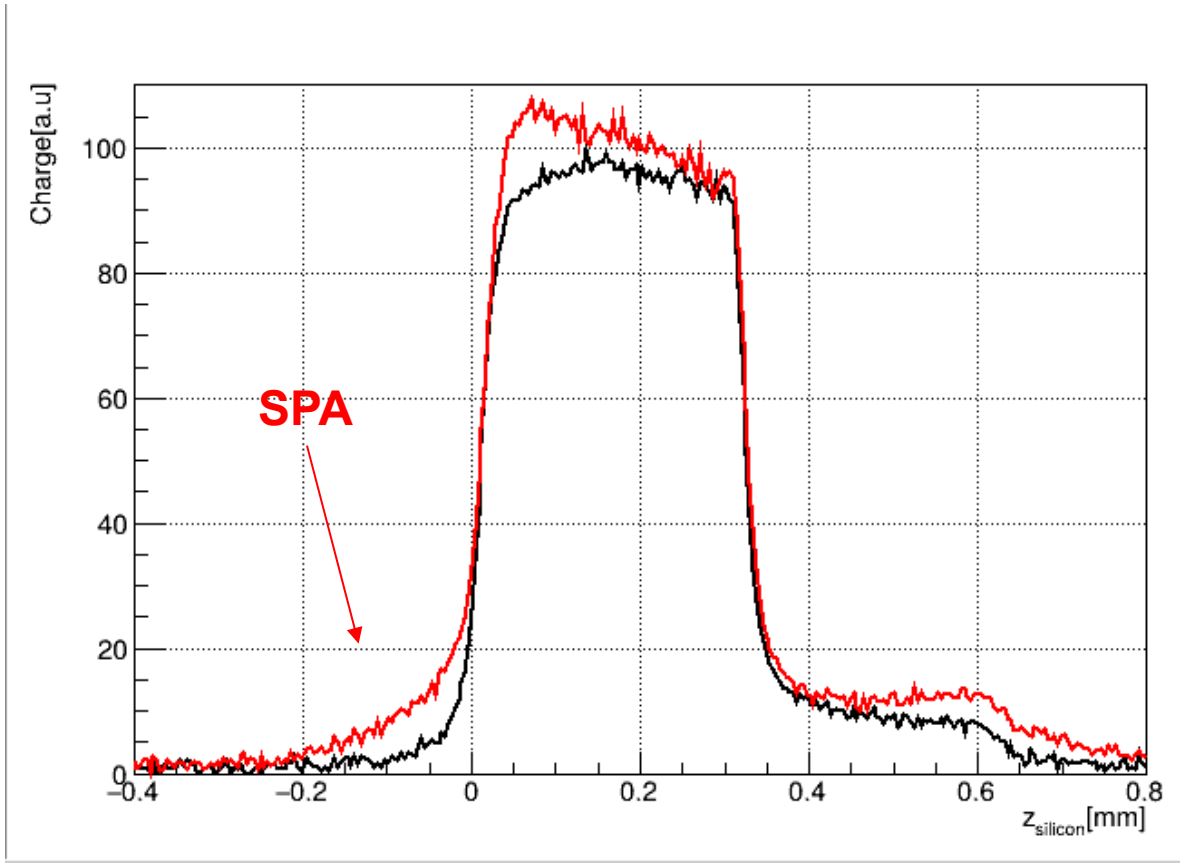
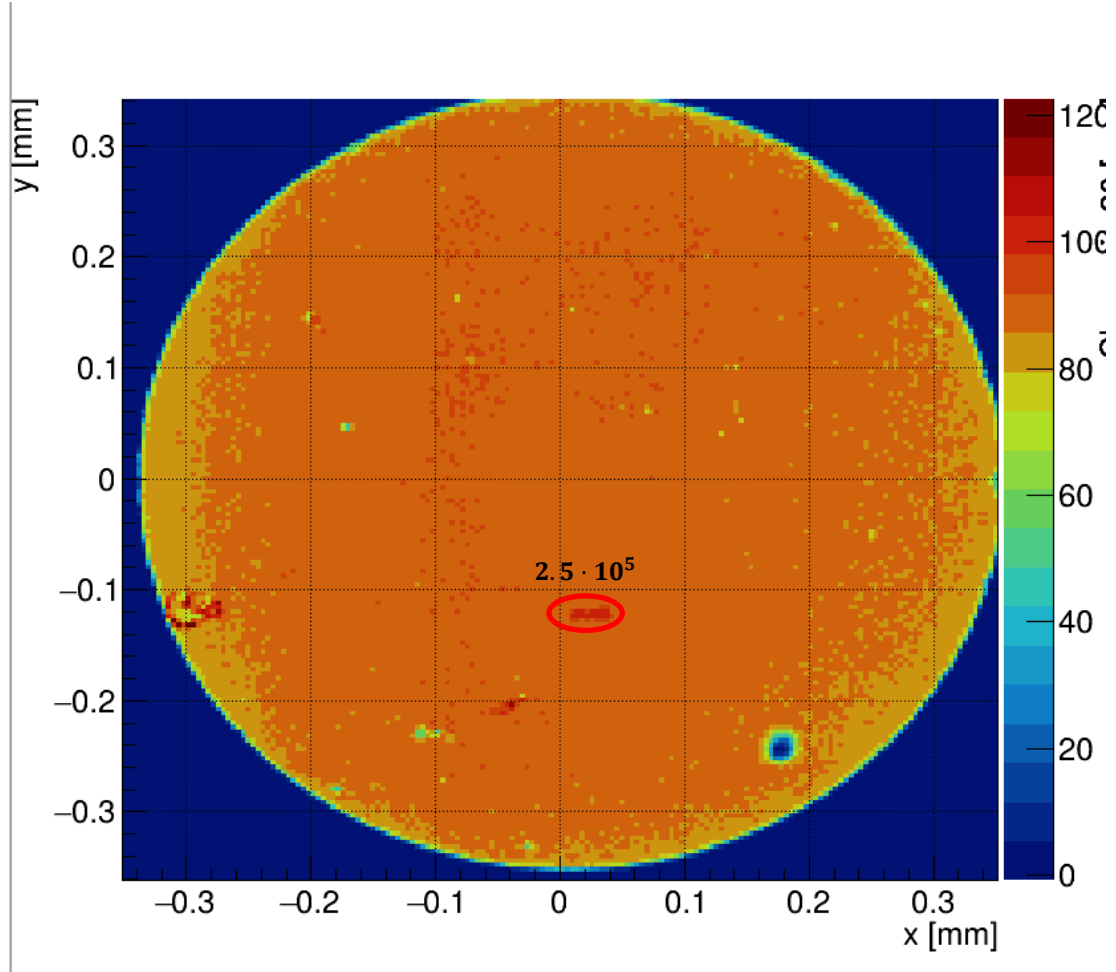


V = 160 V



# TPA-TCT on O implanted DUT

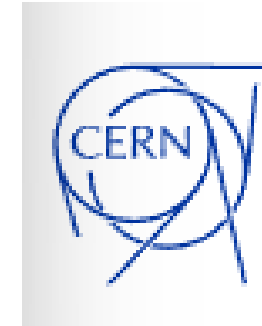
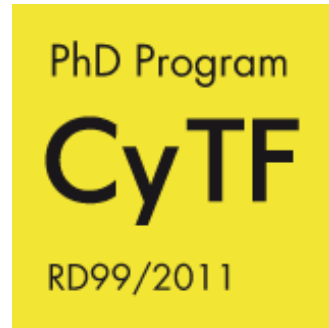
## TPA-TCT: SWIR laser (1550nm = 0.8 eV)



# Summary

- **Controlled ion implantation** of H, O, Si, and N at CNA — down to **a single ion** per spot.
- SPA-TCT and TPA-TCT used at CERN to detect and localize implantation-induced damage.
- **TPA-TCT** shows **high 3D sensitivity**, revealing **charge loss and defect distribution** in silicon.

# Acknowledgments



Actividades del CNA para los "upgrades" de alta luminosidad de CMS y DRDs del ECFA (PID2023-148418NB-C44).



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Actuación 1.1 Irradiación de detectores con aceleradores. (ASTRO21/1.1/1).



# Back-up slides

# Ion implanted

